August 7, 2026

NEWS RELEASE

Enhanced Production Capacity for Ultra-Thin Embedded Capacitance Materials "FaradFlex®"

- Investing a total of 5 billion yen through 2030 to increase production at two existing manufacturing locations and establishing the new plant in Taiwan to increase production capacity five times -

Mitsui Kinzoku Company, Limited (President: Seiji Ikenobu; "Mitsui Kinzoku") announces that it has successfully expanded production capacity for its FaradFlex® thin embedded capacitance materials manufactured at its Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn Bhd) and Ageo Plant, as announced in a news release dated August 21, 2025 ("Enhanced Production Capacity for Ultra-Thin Embedded Capacitance Materials FaradFlex®").

Mitsui Kinzoku has decided on plans to boost its production capacity to five times the 2025 level by increasing production at its existing plants and establishing the new plant in Taiwan.

FaradFlex® is positioned as a growth product following our ultra-thin copper foil MicroThin™ and electrolytic copper foil VSP™ for high-frequency substrates. FaradFlex® is designed to suppress signal noise, which is a significant challenge in the pursuit of faster and higher-capacity information and communication devices. It is utilized in high-performance routers, server, high-layer-count substrates for supercomputers, and MEMS microphones embedded in smartphones. Currently, demand for our products is rapidly increasing in AI infrastructure in particular, in addition to the rising adoption rates in smartphones and wireless headsets. Given the anticipated market growth, we decided to expand production capacity at both existing production sites for FaradFlex®, the Malaysia Plant and Ageo Plant, and also establish the new plant in Taiwan.

We have already completed the expansion of production capacity at the Malaysia Plant and Ageo Plant to a combined 75,000 m^2 per month. Additionally, leading up to FY2030, we will further increase production at the two existing locations and establish the new plant in Taiwan, and anticipate total investments of 5 billion yen across the three locations.

These steps will result in an increase of Mitsui Kinzoku's total production capacity to 355,000 m^2 per month. Mitsui Kinzoku will continue its efforts to additionally increase production capacity to meet the continued growth of demand in the future.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing its vision for 2030, "Building new businesses —and the future— with our material intelligence," based on its purpose, "We promote the well-being of the world through a spirit of exploration and diverse technologies."

■ FaradFlex® production capacity (Unit: thousand m^2 / month) (for reference)

	FY2025	FY2026	FY2027	FY2028	FY2029	FY2030
Malaysia Plant	70	80	100	135	135	135
Ageo Plant	5	5	35	60	85	85
Taiwan (New plant)	-	-	-	-	70	135
Total	75	85	135	195	290	355

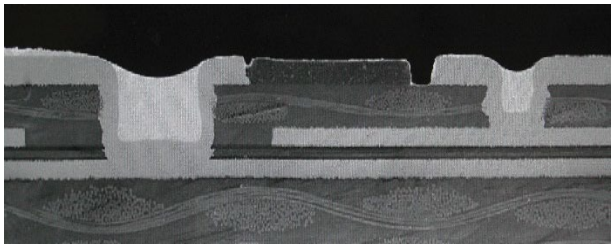
[Contact]
Corporate Communications Department, Corporate Planning & Control Sector, Mitsui Kinzoku Company, Limited
TEL: 03-5437-8028 E-mail: PR@mitsui-kinzoku.com

(Reference)

1. Manufacturing FaradFlex®

FaradFlex® is a material that is composed of ultra-thin dielectric layer (thickness range of 3 to 25 um) with a copper foil on both sides (with a typical thickness range of 18 to 70 μm). FaradFlex® forms a circuit that serves as a capacitor embedded in the PCB.

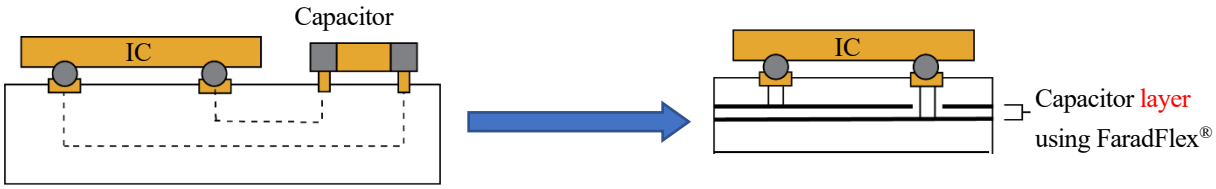
Cross section of PCB incorporating FaradFlex®



FaradFlex® (Three-layer structure of copper foil, dielectric layer, and copper foil)

2. An example of the simulated use of an embedded capacitor

FaradFlex® allows a capacitor layer to be formed immediately below the IC. Signal noise can be reduced by shortening the distance between the IC and the capacitor layer. In addition, the thinness of the dielectric layer also helps to reduce the thickness of PCBs.



FaradFlex® embedded in a PCB